L	Hits	Search Text	DB	Time stamp
Number 1	591015	(plate or board or substrate or article)	USPAT; US-PGPUB;	2003/09/03 10:46
		near5 (resin\$5 or polymer\$5 or plastic or polyimide or non\$2conduct\$8 or insulat\$8 or epoxy)	EPO; JPO; DERWENT; IBM_TDB	
2	129791	((plate or board or substrate or article) near5 (resin\$5 or polymer\$5 or plastic or polyimide or non\$2conduct\$8 or insulat\$8 or epoxy)) and ((plate or board or substrate or article) near5 (via\$3 or hole\$3 or opening\$3 or trench\$3 or	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/03 10:47
3	10	recess\$3 or cavit\$6)) "13" and (electroless\$3 near15 (via\$3 or hole\$3 or opening\$3 or trench\$3 or recess\$3 or cavit\$6))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/09/03 10:53
	1851	article) near5 (resin\$5 or polymer\$5 or plastic or polyimide or non\$2conduct\$8 or insulat\$8 or epoxy)) and ((plate or board or substrate or article) near5 (via\$3 or hole\$3 or opening\$3 or trench\$3 or recess\$3 or cavit\$6))) and (electroless\$3 near15 (via\$3 or hole\$3 or opening\$3 or trench\$3 or recess\$3 or cavit\$6))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/03 10:53
5	951		USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/03
6	498		DERWENT; IBM_TDB	2003/09/03
	135		DERWENT; IBM_TDB	2003/09/03 12:00

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	11410	1d-u add balla	USPAT;	2003/09/03
9	11419	solder adj balls	US-PGPUB;	12:06
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	2002/00/02
10	4372	((plate or board or substrate or article)	USPAT;	2003/09/03
1		near5 (resin\$5 or polymer\$5 or plastic or polyimide or non\$2conduct\$8 or insulat\$8	US-PGPUB; EPO; JPO;	12.07
		or epoxy)) and (solder adj balls)	DERWENT;	1
		of epoxy), and (sorder adj barrs)	IBM TDB	
11	4009	(((plate or board or substrate or	USPAT;	2003/09/03
		article) near5 (resin\$5 or polymer\$5 or	US-PGPUB;	12:07
		plastic or polyimide or non\$2conduct\$8 or	EPO; JPO;	
	!	insulat\$8 or epoxy)) and (solder adj	DERWENT;	
		balls)) and (via\$3 or trench\$3 or hole\$3 or opening\$3 or recess\$3 or groove\$3 or	IBM_TDB	
		cavit\$8)		
12	1799	((((plate or board or substrate or	USPAT;	2003/09/03
		article) near5 (resin\$5 or polymer\$5 or	US-PGPUB;	12:09
		plastic or polyimide or non\$2conduct\$8 or	EPO; JPO;	
		insulat\$8 or epoxy)) and (solder adj	DERWENT;	
i		balls)) and (via\$3 or trench\$3 or hole\$3 or opening\$3 or recess\$3 or groove\$3 or	IBM_TDB	
1		cavit\$8)) and wiring		
13	1496	(((((plate or board or substrate or	USPAT;	2003/09/03
		article) near5 (resin\$5 or polymer\$5 or	US-PGPUB;	12:08
		plastic or polyimide or non\$2conduct\$8 or	EPO; JPO;	
		insulat\$8 or epoxy)) and (solder adj	DERWENT;	
	ĺ	balls)) and (via\$3 or trench\$3 or hole\$3 or opening\$3 or recess\$3 or groove\$3 or	IBM_TDB	1
		cavit\$8)) and wiring) and pad\$3		
15	93	(((((plate or board or substrate or	USPAT;	2003/09/03
		article) near5 (resin\$5 or polymer\$5 or	US-PGPUB;	12:09
İ	1	plastic or polyimide or non\$2conduct\$8 or	EPO; JPO;	
1		insulat\$8 or epoxy)) and (solder adj balls)) and (via\$3 or trench\$3 or hole\$3	DERWENT; IBM TDB	
		or opening\$3 or recess\$3 or groove\$3 or	TBM_TDB	
		cavit\$8)) and wiring) and pad\$3) and		
		(press\$2forming or (injection adj	ļ	
		mold\$5))		0000/00/00
16	90	(((((((plate or board or substrate or	USPAT;	2003/09/03
		article) near5 (resin\$5 or polymer\$5 or plastic or polyimide or non\$2conduct\$8 or	US-PGPUB; EPO; JPO;	12:09
		insulat\$8 or epoxy)) and (solder adj	DERWENT;	
		balls)) and (via\$3 or trench\$3 or hole\$3	IBM TDB	
		or opening\$3 or recess\$3 or groove\$3 or	_	
1		cavit\$8)) and wiring) and pad\$3) and		
	1	(press\$2forming or (injection adj		
		<pre>mold\$5))) not ((((((plate or board or substrate or article) near5 (resin\$5 or</pre>		
1		polymer\$5 or plastic or polyimide or		
		non\$2conduct\$8 or insulat\$8 or epoxy))		
		and ((plate or board or substrate or		
		article) near5 (via\$3 or hole\$3 or		,
		opening\$3 or trench\$3 or recess\$3 or		
		<pre>cavit\$6))) and (electroless\$3 near15 (via\$3 or hole\$3 or opening\$3 or trench\$3</pre>		
		or recess\$3 or cavit\$6))) and		
		((electroplat\$10 or electrodeposit\$10 or		
		electroly\$10 or electrochem\$10) near15		
		(via\$3 or hole\$3 or opening\$3 or trench\$3		
		or recess\$3 or cavit\$6))) and wiring) and		